

Corrigendum-1 to GeM Bid ref: GEM/2024/B/5192015 dated 22/07/2024 for Supply, Installation, Configuration and Maintenance of 30 nos. of All-in-One computers with three (03) years warranty and two (02) years AMC in Canara Bank.

It is decided to amend the following in respect of the above RFP:

a. GeM bid document (Bid End date/ Bid Opening Date, Page no. 1 of 7):

Description	Existing details	Amended details	
Bid End Date/Time	12/08/2024, 15:00:00	<u>16/08/2024</u> , 15:00:00	
Bid opening Date/Time	12/08/2024, 15:30:00	<u>16/08/2024</u> , 15:30:00	

<u>b.</u>

SI No	Section/Annexu re/Appendix of GeM Bid	Clause No.	Existing Clause	, Amended Clause
7.	ATC Annexure-10 Technical Specifications	Annexure-10 Technical Specifications	Annexure-10 Technical Specifications	Amended Annexure-10 Technical Specifications

All the other instructions and terms & conditions of the above RFP shall remain unchanged.

Please take note of the above amendments while submitting your response to the subject RFP.

Date: 07/08/2024 Place: Bengaluru

Deputy General Manager





Amended Annexure-10 Technical Specifications

SUB: RFP for Supply, Installation, Configuration and Maintenance of 30 nos. of All-in-One computers with three (03) years warranty and two (02) years AMC in Canara Bank.

Ref: GEM/2024/B/5192015 dated 22/07/2024.

Note:			
(a)	If the bidder feels that certain features offered are superior to what has been specified by the Bank, it shall be highlighted separately. Information regarding any modification required in the proposed solution to meet the intent of the specifications and state-of-the-art technology shall be provided. However, the Bank reserves the right to adopt the modifications /superior features suggested/ offered.		
(b)	The bidder shall provide all other required equipments and/or services, whether or not explicitly mentioned in this RFP, to ensure the intent of specification, completeness, operability, maintainability and upgradability.		
(c)	The selected bidder shall own the responsibility to demonstrate that the product offered are as per the specification/performance stipulated in this RFP and as committed by the bidder either at site or in bidder's work site without any extra cost to the Bank.		

All points mentioned under are mandatory to comply and non-compliance to any of the point lead to disqualification of the bidder during evaluation.

Technical Specification of All-in-one Computers

SI. No.	Functionality	Description	Bidder Compliance (Yes/No)	Remarks
a	Make (Commercial - Enterprise Model)	Must be specified and relevant brochure must be enclosed.		
Ь	Model Name & No.	Must be specified		
С	Form Factor	"All-in-one" with USB key board and mouse. All-in-One with stand and tilt feature.		
d	Monitor	Minimum 21" with Antiglare and LED Backlight. Aspect Ratio of 16:9, 1000:1 (Contrast Ratio). Resolution Full HD (1920x1080), Built in speaker.		
е	CPU	 Intel Core i7-13700T (Performance Base Frequency 1.4GHz up to 4.9GHz; Minimum 10 Cores; 30MB Cache) or higher. Or Equivalent AMD Ryzen 7 Processor or higher. If Bidder is quoting an equivalent or higher processor, the Bidder has to submit the Benchmark Certificate (with benchmarking score) from anyone of the following two benchmarking agencies stating that the quoted 		

		,	,	r
	ŀ	Processor is an equivalent or		
		higher processor.		
		a. Sys Mark 2018		
		b. PC Mark 10.		
		3. Bidder should quote Processor		
		with Minimum specification of		
		"2.30 GHz base frequency, 4.50		
		Ghz Turbo frequency, 16MB		
		Cache, 8 cores, 16 threads"		
		Minimum 1X16 GB DDR4 RAM-2666		
f	Memory	MHz expandable upto <u>64 GB</u> or more		
		with minimum 2 DIMM Slots.		
		OEM logo should be embossed on the		
"	Mother Board	mother board (Sticker is not		i
g	Motifei Boaid	acceptable). System should be able		
		to support OS - 64 bit.		
		Intel / AMD Chipset with minimum		
		Bus Speed of 8GT/s.		
h	Chipset			
		Processor and Chipset should be		
		from same OEM.		
		Intel UHD Graphics or equivalent		
i	Graphics	AMD Radeon or higher with minimum		
		2 GB shared/dedicated memory.		,
ł	Processor			•
j	Thermal Design	35 W or less		
	Power (TDP)			
	Bus	$1 \times M.2 2230$; $1 \times M.2 2280$ ($1 \times$		
k	architecture	M.2 slot for NW & 2 x M.2 2280		
	arcinicatura	slots for storage.) or higher.	*****	
1	Hard Disk Drive	Minimum 512 GB SSD NVME + 1 TB	.	
<u> </u>		HDD		
		100/1000 Mbps integrated Ethernet		
m	Networking	card with remote booting facility,		-
	facility	remote system installation, remote		
		wake up compatible.		
n	Wireless	Integrated wireless 802.11 ac dual		
	Connectivity	band		
		1. Five (5) USB ports or higher on		
		board (min. 2 USB 3.0 ports) /		
		Four (4) USB ports on board (min.		
		2 USB 3.0 ports) and USB 3.0 Hub		!
	Down	with minimum 35cms cable (min.		
0	Ports	4 ports)		
		2. One (1) serial audio ports for		
		microphone & head phones		
1		/(Combo)		
		3. Rj45 Ethernet port,		
ļ		4. HDMI 2.0 or above / Display Port.		
	C	Full HD web cam with at least 70		
Р	Camera	Degree view angle (Field of View)		
		and integrated microphone.		
q	Key Board	104 Keys Mechanical (Windows &		
J " .	,	Linux Compatible) with Rupee		

	V /					
		symbol on keyboard with 50 Million				
		characters keystroke life.				
r	Mouse	Two button optical scroll Mouse of OEM Make with Mouse Pad.				
S	Power Supply	OEM Standard External Power Supply (Adaptor with Input :100-240 V, 50-60 Hz).				
t	Operating System (OS)	Genuine Windows 10 Professional or latest version of Windows Professional OS, with 64 Bit should be pre-installed in the All-in-One. Desktop Computers. Recovery media should be loaded in the D drive of the Hard Disk of the All-in-One Desktop Computers.				
u	Certifications	BIS, BEE, RoHS, EPR and any other Indian Certificate				
v	Other Technical Requirements	 OS installation/re-installation should be done by the successful bidder in case of any error/corrections/corruption in OS without any extra cost to the Bank. Bank will inform the partition at the time of placing LOI/Order. Bidder has to configure the Backup of the Drive in the nearest AIO/PC available at the Branch/Office. 				
х	Security	TPM 2.0 Security Chip (discrete/integrated/firmware).				

Note:

- 1. The Bidder shall specifically mention the make and model of the items offered for all the requirements in terms of RFP without fail, failing which the Bid is liable for rejection.
- 2. If the Bidder feels that certain features offered are superior to what has been specified by the Bank, it shall be highlighted separately. Information regarding any modification required in the proposed configuration to meet the intent of the specifications and state-of-the-art technology shall be provided. However, the Bank reserves the right to accept the modifications / superior features suggested/offered.
- 3. The Bidder shall provide all other required equipments and services, whether or not explicitly mentioned in this RFP, to ensure the intent of specification, completeness, operability, maintainability and upgradability.
- 4. The selected bidder shall own the responsibility to demonstrate that the products offered are as per the specification/performance stipulated in this RFP and as committed by the bidder either at site or in bidder's work site without any extra cost to the Bank.

We hereby comply with the above Technical Specification without any deviations.

Date

Signature with seal Name: Designation:

